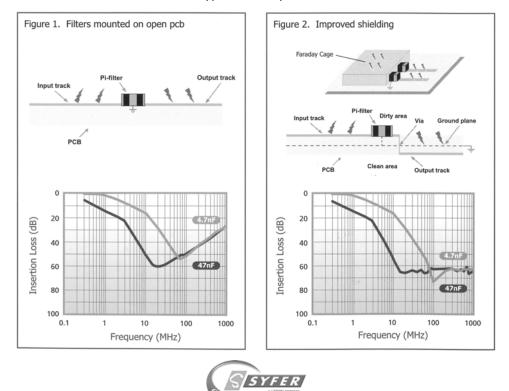


Effects of mounting method on insertion loss

C and Pi filters are mounted to PCBs and soldered in identical manner to chip capacitors. Solder connections made to each end (signal lines) and each side band (earth track).

Whilst SBSG, SBSM and SBSP filters can be mounted conventionally on PCBs, they are also suitable for mounting in a wall or partition on a board. This greatly improves the screening between filter input and output, thereby enhancing the high frequency response.

The following insertion loss curves (for SBSP, SBSG, SBSM Pi filters), based on actual measurements, show the effect. It can be seen that the filters conventionally mounted (Fig. 1) exhibit a drop in attenuation at higher frequencies. Improved shielding methods (Fig. 2), maintain excellent suppression characteristics to 1GHz and above. See below for application example.



MP.

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Insertion loss tables for surface mount EMI filters - C filter

Typical No-Load Insertion Loss (dB)*

Product Code	Packing	Capacitance (±20%)	Dielectric	Rated Voltage (dc)	DWV (dc)	Approximate Resonant Frequency (MHz)	0.1MHz	1MHz	10MHz	100MHz	1GHz
SBSMC5000102MX		1.0nF	X7R	500	750	270	0	0	5	24	21
SBSMC5000152MX		1.5nF	X7R	500	750	265	0	0	7	25	21
SBSMC5000222MX		2.2nF	X7R	500	750	235	0	0	11	31	21
SBSMC5000332MX	s) Is)	3.3nF	X7R	500	750	185	0	1	15	35	21
SBSMC5000472MX	reels) ' reels)	4.7nF	X7R	500	750	154	0	2	17	40	21
SBSMC5000682MX	7″ 13″	6.8nF	X7R	500	750	125	0	4	21	44	21
SBSMC5000103MX	ed / m	10nF	X7R	500	750	100	0	5	24	50	21
SBSMC5000153MX	Packed 178mm 330mm /	15nF	X7R	500	750	80	0	7	27	43	21
SBSMC5000223MX	$\cong \cong \textcircled{m}$	22nF	X7R	500	750	65	0	11	31	43	21
SBSMC5000333MX	B = Bull and-Reel and-Reel	33nF	X7R	500	750	54	1	15	34	43	21
SBSMC5000473MX	B -and	47nF	X7R	500	750	46	2	17	37	43	21
SBSMC5000683MX	lape-	68nF	X7R	500	750	39	3	21	41	43	21
SBSMC2000104MX	н <u>6</u> = =	100nF	X7R	200	500	33	5	24	44	43	21
SBSMC2000154MX	⊢ Ω "	150nF	X7R	200	500	26	7	26	47	43	21
SBSMC1000224MX		220nF	X7R	100	250	21	11	31	52	43	21
SBSMC1000334MX		330nF	X7R	100	250	20	14	33	54	43	21
SBSMC0500474MX		470nF	X7R	50	125	19	17	36	54	43	21

* - Insertion Loss performance quoted is measured on an open board mounted on a brass backplane in a 50Ω system. Performance curves can be supplied on request. Performance in circuit is liable to be different and is affected by board material, track layout, grounding efficiency and circuit impedances. Shielding can be used to improve high frequency performance.

Insertion loss tables for surface mount EMI filters - P filter

								vical No-Lo	ad Insert	ion Loss (dB)*
Product Code	Packing	Capacitance (±20%)	Dielectric	Rated Voltage (dc)	DWV (dc)	Approximate Resonant Frequency (MHz)	0.1MHz	1 MHz	10MHz	100MHz	1GHz
SBSMP5000102MX		1.0nF	X7R	500	750	150	0	0	5	34	21
SBSMP5000152MX		1.5nF	X7R	500	750	130	0	0	7	39	21
SBSMP5000222MX		2.2nF	X7R	500	750	100	0	0	11	38	21
SBSMP5000332MX	s) Is)	3.3nF	X7R	500	750	80	0	1	12	44	21
SBSMP5000472MX	reels) (reels)	4.7nF	X7R	500	750	63	0	2	15	44	21
SBSMP5000682MX	7″ r 13″	6.8nF	X7R	500	750	55	0	3	18	44	21
SBSMP5000103MX	ed / mr /	10nF	X7R	500	750	43	0	5	24	44	21
SBSMP5000153MX	Packed (178mm 330mm	15nF	X7R	500	750	35	0	8	28	44	21
SBSMP5000223MX	$\leq \bigcirc \bigcirc$	22nF	X7R	500	750	30	0	10	35	44	21
SBSMP5000333MX	B = Bulk -and-Reel and-Reel	33nF	X7R	500	750	23	1	12	48	44	21
SBSMP5000473MX		47nF	X7R	500	750	19	2	16	50	44	21
SBSMP5000683MX	Tape-	68nF	X7R	500	750	15	3	19	55	44	21
SBSMP2000104MX	Т = Та R = Та	100nF	X7R	200	500	12	5	21	58	44	21
SBSMP2000154MX		150nF	X7R	200	500	10	8	23	62	44	21
SBSMP1000224MX		220nF	X7R	100	250	8	11	25	63	44	21
SBSMP1000334MX		330nF	X7R	100	250	6	14	22	62	44	21
SBSMP0500474MX		470nF	X7R	50	125	5	16	20	64	44	21

* - Insertion Loss performance quoted is measured on an open board mounted on a brass backplane in a 50Ω system. Performance curves can be supplied on request. Performance in circuit is liable to be different and is affected by board material, track layout, grounding efficiency and circuit impedances. Shielding can be used to improve high frequency performance.

Ordering Information

SBS	М	Р	050	0474	М	Х	т
Туре	Size	Configuration	Rated Voltage	Capacitance in Pico farads (pF)	Tolerance	Dielectric	Packaging
Surface mount board filter	M = 2220	C = C section P = Pi Section	050 = 50Vdc 100 = 100Vdc 200 = 200Vdc 500 = 500Vdc	First digit is 0. Second and third digits are significant figures of capacitance code. The fourth digit is number of zeros following. Example: 0471 = 470nF	M = ±20%	X = X7R	T=178mm (7") reel R=330mm (13") reel B = Bulk

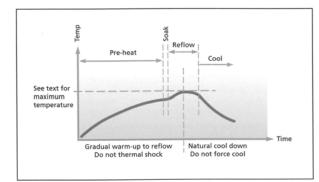
Reeled Quantities

170 mana (7%) ma al	2220	220mm (12%) mod	2220
178mm (7") reel	500	330mm (13") reel	2000

Surface mount and panel mount solder-in filters

Solder pad layouts are included with the detailed information for each part.

Recommended soldering profile



Soldering of filters

The soldering process should be controlled such that the filter does not experience any thermal shocks which may induce thermal cracks in the ceramic dielectric.

The pre-heat temperature rise of the filter should be kept to around 2°C per second. In practice successful temperature rises tend to be in the region of 1.5°C to 4°C per second dependent upon substrate and components.

The introduction of a soak after pre-heat can be useful as it allows temperature uniformity to be established across the substrate thus preventing substrate warping. The magnitude or direction of any warping may change on cooling imposing damaging stresses upon the filter.

E01, E03, E07 SBSP ranges are compatible with all standard solder types including lead-free, maximum temperature

260°C. For SBSG, SBSM and SFSS ranges, solder time should be minimised, and the temperature controlled to a maximum of 220°C. For SFSR, SFST and SFSU ranges the maximum temperature is 250°C.

Cooling to ambient temperature should be allowed to occur naturally. Natural cooling allows a gradual relaxation of thermal mismatch stresses in the solder joints. Draughts should be avoided. Forced air cooling can induce thermal breakage, and cleaning with cold fluids immediately after a soldering process may result in cracked filters.

Note: The use of FlexiCap[™] terminations is strongly recommended to reduce the risk of mechanical cracking.

Soldering to axial wire leads

Soldering temperature

The tip temperature of the iron should not exceed 300°C. Dwell time

Dwell time should be 3-5 seconds maximum to minimise the risk of cracking the capacitor due to thermal shock.

Heat sink

Where possible, a heat sink should be used between the solder joint and the body, especially if longer dwell times are required.

Bending or cropping of wire leads

Bending or cropping of the filter terminations should not be carried out within 4mm (0.157'') of the epoxy encapsulation, the wire should be supported when cropping.

A more comprehensive application note covering installation of all Syfer products is available on the Syfer website.

Mouser Electronics

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Knowles:

SBSMP5000472MXT	SBSMP1000334MX1	SBSMP5000102MXT	SBSMP0500474MXT	SBSMP5000103MXT		
SBSMP5000683MXT	SBSMP2000154MXT	SBSMP5000153MXT	SBSMP5000473MXT	SBSMP2000104MXT		
SBSMP5000223MXT	SBSMP1000224MXT	SBSMC1000334MXB	SBSMC5000683MXT	SBSMC5000103MXT		
SBSMP5000682MXT	SBSMC0500474MXB	SBSMP5000683MXB	SBSMP5000332MXB	SBSMP5000103MXB		
SBSMP5000222MXB	SBSMP5000682MXB	SBSMP5000152MXB	SBSMC5000683MXB	SBSMP2000154MXB		
SBSMC5000103MXB	SBSMC2000154MXT	SBMP1000334MXB/0	069 SBSMC5000103M	IXT/0107		
<u>SBSMP5000102MXT/0107</u> <u>SBSMP5000473MXB</u> <u>SBSMP5000473MXT/0107</u> <u>SBSMP5000472MXT/0107</u>						